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Edwards STP-iXA2206C Technical Specifications

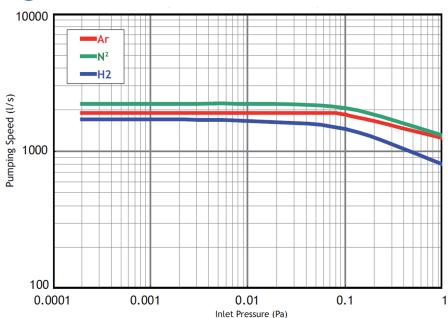
| Inlet flange size | ISO250F/VG250 | ISO250F/VG250/ICF305 | | |
|---|--|----------------------|--|--|
| Backing port size | KF40 | | | |
| Pump speed N ₂ /Ar | 2200/1900 | Litres/second | | |
| Compression ratio N ₂ /H2 | >10 ⁸ / 1 x 10 ⁴ | | | |
| Ultimate pressure | 10 ⁻⁷ (10 ⁻⁹) | Pa (Torr) | | |
| Allowable backing pressure | 266 (2) | Pa (Torr) | | |
| Max gas flow N_2^{*1} (water cooled only) | 3000 (5.07) | sccm (Pa m³/sec) | | |
| Max gas flow Ar *1 (water cooled only) | 1400 (2.36) | sccm (Pa m³/sec) | | |
| Rated speed | 27000 | rpm | | |
| Run-up time to 90% rated speed | <8 | minutes | | |
| Mounting position | Any orientation | | | |
| Input voltage | 200-240 | V | | |
| Maximum input power (without TMS) | 1200 | VA | | |
| Weight | 62 | kg | | |
| | | | | |

 $^{^{*1}}$: The maximum gas flow is applicable under conditions that N $_2$ or Ar gas is pumped continuously with water cooling temperature between 15-25° C and the backing pump (10,000 l/min size) is used. It is changed on condition.

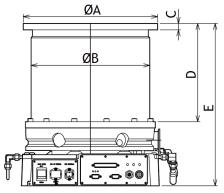
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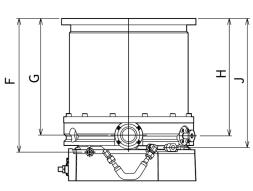
Edwards STP-iXA2206C

Pumping Curves



Dimensions





VG250

350

296

18

235

395

312

281

283

322

ISO250F

335

296

16

245

405

322

291

293

332

Inlet port flange

ØΒ

D

F

G

| <u>V</u> | V | <u></u> |
|----------|---|---------|
| | | |
| ICF305 | | |
| 305 | | |
| 296 | | |
| 28 | | |
| 275 | | |
| 435 | | |
| 352 | | |
| 321 | | |
| 323 | | |

322

| 344 | 317 213 | 20 20 20 20 20 20 127 150 | 80 | 5° \\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | 2002 2088 |
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Edwards STP-iXA2206C

Features & Benefits

- compact design, including fully integrated controller
- innovative, self-sensing magnetic bearing system
- · digital 5-axis control
- vibration levels reduced by 50% compared to existing turbos
- can be configured to run corrosive processes
- · easy installation, small footprint
- no oil prevents contamination

Applications

 plasma etch · ECR etch · film deposition · sputtering · beam line pumping & station · ion implantation source

